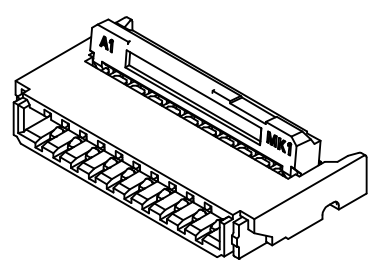
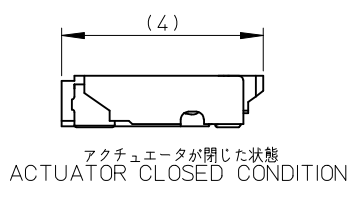
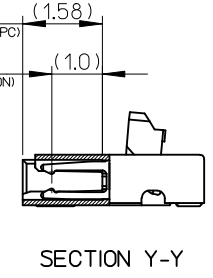
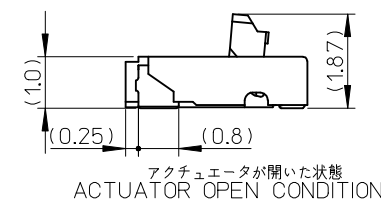
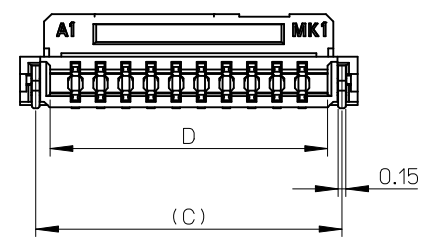


メタルマスク : 0.1mm  
 開口部 : TERM.(0.7X0.3)  
 NAIL(1.0X0.3)  
 METAL MASK THICKNESS : 0.1mm  
 OPENING AREA : TERM.(0.7X0.3)  
 NAIL(1.0X0.3)



16.5	17.08	15.5	17.7	503480-3200	32
13.5	14.08	12.5	14.7	503480-2600	26
11.5	12.08	10.5	12.7	503480-2200	22
10.5	11.08	9.5	11.7	503480-2000	20
9.5	10.08	8.5	10.7	503480-1800	18
9.0	9.58	8.0	10.2	503480-1700	17
8.5	9.08	7.5	9.7	503480-1600	16
7.5	8.08	6.5	8.7	503480-1400	14
6.5	7.08	5.5	7.7	503480-1200	12
5.5	6.08	4.5	6.7	503480-1000	10
4.5	5.08	3.5	5.7	503480-0800	8
3.5	4.08	2.5	4.7	503480-0600	6
2.5	3.08	1.5	3.7	503480-0400	4
D	C	B	A	EMBOSSED PACKAGE	極数
				オーダー番号 ORDER NO.	CIRCUIT

CONNECTOR SERIES No. 503480-\*\*\*09

REVISED EC NO: KOR2013-0037 DRWN:YRBAE 2012/09/24 CHKD: APPR:YSK IM02 2012/09/26 REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY THIRAYAMA	DATE 2009/12/11	TITLE 0.5 FPC CONN. E/O BACKFLIP H=1.0MM ASSEMBLY		
	10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2009/12/11	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/10/13	DOCUMENT NO. SD-503480-001	SHEET NO. 1 OF 2	
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

NOTES

1. 部品構成

PART COMPOSITION

ハウジング・・・材質：液晶ポリマー（LCP）、ガラス充填、UL94V-0、ナチュラル（白）  
HOUSING MATERIAL: LIQUID CRYSTAL POLYMER(LCP) GLASS FILLED, UL94V-0, NATURAL(WHITE)

ターミナル・・・材質：燐青銅  
TERMINAL MATERIAL: PHOSPHOR BRONZE

CONTACT AREA: SEPARATED GOLD PLATING (0.1 MICROMETER MINIMUM)  
SOLDER TAIL AREA: SEPARATED GOLD PLATING  
UNDERPLATE: NICKEL OVERALL (1.0 MICROMETER MINIMUM)

アクチュエータ・・・材質：ポリアミド（PA）、ガラス充填、UL94 HB、黒色  
ACTUATOR MATERIAL: POLYAMIDE(PA) GLASS FILLED, UL94 HB, BLACK

ネイル・・・材質：燐青銅  
NAIL MATERIAL: PHOSPHOR BRONZE

CONTACT AREA: SEPARATED GOLD PLATING (0.1 MICROMETER MINIMUM)  
SOLDER TAIL AREA: SEPARATED GOLD PLATING  
UNDERPLATE: NICKEL OVERALL(1.0 MICROMETER MINIMUM)

2. 基板実装前にアクチュエータを操作しないで下さい。

PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.

3. 必ずFPCを挿入してからアクチュエータを操作して下さい。

PLEASE OPERATE THE ACTUATOR AFTER INSERTING THE FPC INTO THE CONNECTOR.

4. FPCについて

ABOUT FPC

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。

接着剤は熱硬化接着剤を推奨します。

尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

RECOMMENDED STIFFENER MATERIAL: POLYIMIDE  
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER  
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE  
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

打抜き方向は導体側から補強板側を推奨致します。

導体部については軟銅箔35μmを推奨致します。

RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
RECOMMENDED CONDUCTOR SPECIFICATION: THICKNESS OF SOFT COPPER FOIL: 35MICROMETER

△5 R0.3は、FPC導体部にかからないこと。

R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

△6 ELV及びRoHS適合品

ELV AND ROHS COMPLIANT

△7 平坦度: 0.1以下

COPLANARITY: 0.1 MAXIMUM

△8 製造上の都合により機能を阻害しない部位の形状を変更する可能性があります。

PLEASE RECOGNIZE A POSSIBILITY TO CHANGE THE SHAPE OF THE PART THAT DOES NOT OBSTRUCT A FUNCTION, BY CIRCUMSTANCES IN OUR PRODUCTION.

△9 本製品の納入状態はアクチュエータが開いた状態となります。

THIS PRODUCT IS DELIVERED WITH THE ACTUATOR IN THE OPEN POSITION.

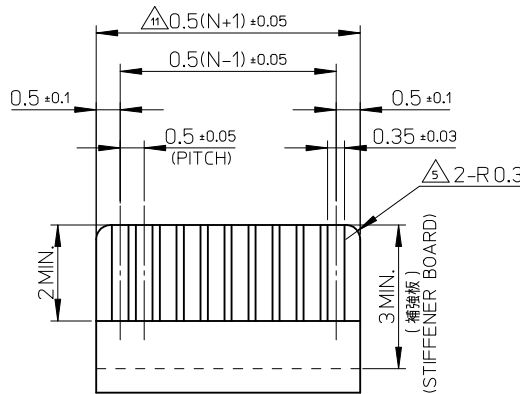
△10 本製品は両面(上面、下面)接触に対応しております。

THIS PRODUCT IS DUAL-CONTACT

(TOP- AND BOTTOM-CONTACTS) TYPE CONNECTOR.

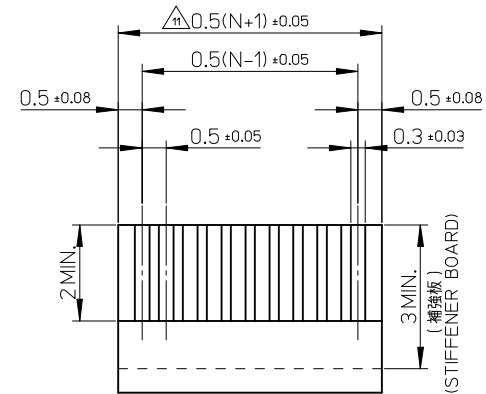
△11 FPC幅が0.5(N+1)+0.02を超える場合、FPC挿入性の事前確認をお願いします。

PLEASE CONFIRM TO INSERT FPC IN ADVANCE WHEN FPC WIDTH IS OVER 0.5(N+1)+0.02.



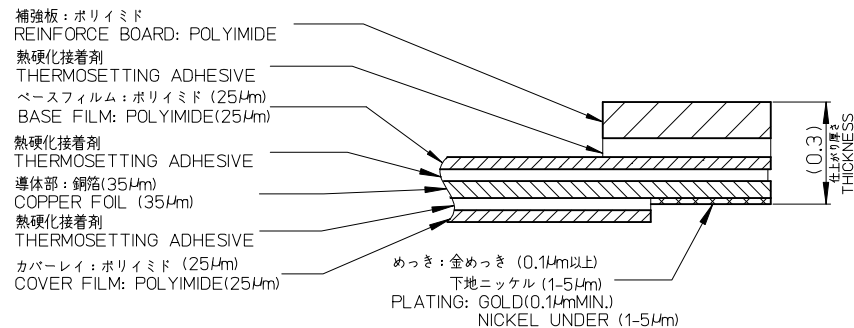
適合FPC推奨寸法  
APPLICABLE FPC  
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.05) : 30極以下に適用  
(THICKNESS: 0.3±0.05) : 30 OR LESS CIRCUITS  
(仕上がり厚さ: 0.3±0.03) : 31極以上に適用  
(THICKNESS: 0.3±0.03) : 31 OR OVER CIRCUITS



適合FFC推奨寸法  
APPLICABLE FFC  
RECOMMENDED DIMENSION

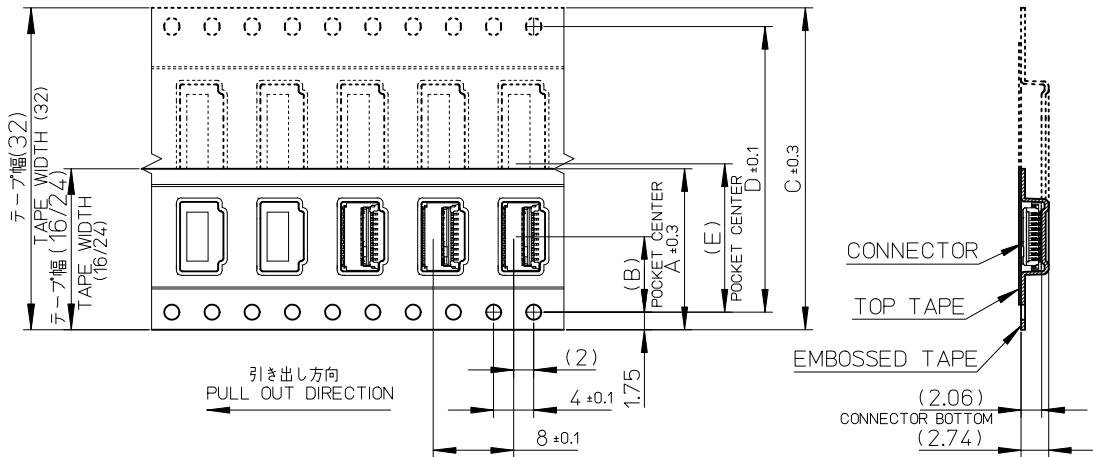
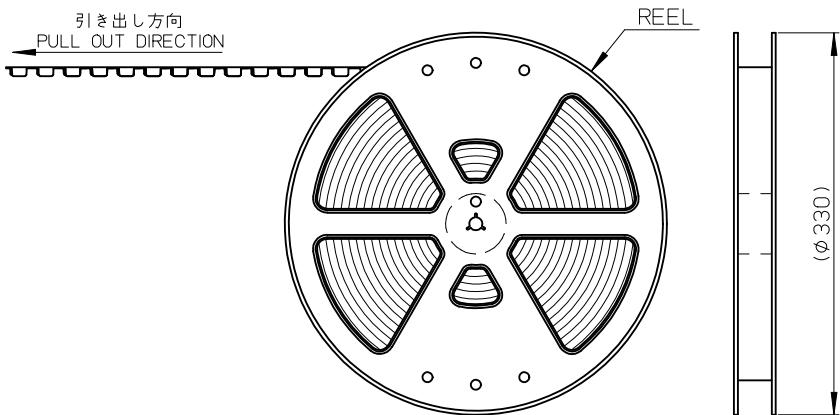
(仕上がり厚さ: 0.3±0.05) : 30極以下に適用  
(THICKNESS: 0.3±0.05) : 30 OR LESS CIRCUITS  
(仕上がり厚さ: 0.3±0.03) : 31極以上に適用  
(THICKNESS: 0.3±0.03) : 31 OR OVER CIRCUITS



FPC構成推奨仕様  
STRUCTURE OF FPC

SEE SHEET 1 EC NO: KOR2013-0037 DRAWN: YBRAE 2012/09/24 CHKD: APPR: YSK IM02 2012/09/26 DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY THIRAYAMA	DATE 2009/12/11	TITLE 0.5 FPC CONN. E/O BACKFLIP H=1.0MM ASSEMBLY	
	10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2009/12/11	APPROVED BY KMORIKAWA	
	30 OVER	±0.3	DATE 2010/10/13	MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-503480-001
	ANGULAR ±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
					SHEET NO. 2 OF 2	

10 9 8 7 6 5 4 3 2 1

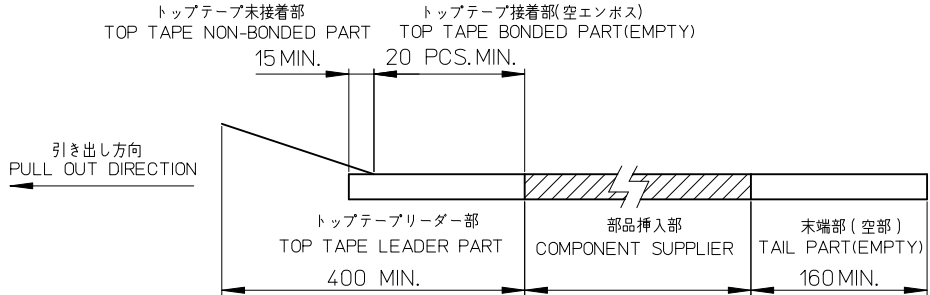


NOTES

1. 製品(503480-\*\*-09)の詳細寸法については、SD-503480-001をご参照下さい。  
 IN THE PACKAGE, PART NO.503480-\*\*-09 DETAILED DIMENSIONS.  
 REFER TO SD-503480-001.

2. 梱包数量 : 3000個/リール  
 NUMBER OF CONNECTORS : 3000PCS/REEL

3. リードテープの長さ  
 LEAD TAPE LENGTH



4. 材料  
 キャリアテープ : PET  
 トップテープ : PET, OTHER  
 リール : PS<リサイクル材を含む>  
 MATERIAL  
 CARRIER TAPE : PET  
 TOP TAPE : PET, OTHER  
 REEL : PS <RECYCLE MATERIAL CONTAINED>

5. カバーテープの剥離強度については、IEC60286-3に準拠  
 COVER TAPE PEEL FORCE IS DEFINED BY IEC60286-3.

エンボステープ内の製品の向き  
 DIRECTION OF CONNECTOR IN EMBOSSED TAPE

14.2	28.4	32	-	-	32	503480-3200	32
-	-	-	11.5	24	24	503480-2600	26
-	-	-	-	-	-	503480-2200	22
-	-	-	-	-	-	503480-2000	20
-	-	-	-	-	-	503480-1800	18
-	-	-	-	-	-	503480-1700	17
-	-	-	-	-	-	503480-1600	16
-	-	-	-	-	-	503480-1400	14
-	-	-	-	-	-	503480-1200	12
-	-	-	7.5	16	16	503480-1000	10
-	-	-	-	-	-	503480-0800	8
-	-	-	-	-	-	503480-0600	6
-	-	-	-	-	-	503480-0400	4
E	D	C	B	A	テープ幅 TAPE WIDTH	オーダー番号 ORDER NO.	極数 CIRCUIT

REVISED EC NO: J2011-0104 DRWNSHIRATA 2010/08/30 CHKD:KAKAHASHI 2010/09/28 APPR:KMORIKAWA 2010/10/01	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY THIRAYAMA	DATE 2009/12/11	TITLE 0.5 FPC CONN. E/O EMBOSSED TAPE PACKAGE			
		10 OVER 30 UNDER	±0.25	CHECKED BY NMATSUURA	DATE 2009/12/11	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2009/12/11	DOCUMENT NO. SD-503480-002			
REV		ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	